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(54) Title: METHOD OF BONDING A FIRST SUBSTRATE AND A SECOND SUBSTRATE

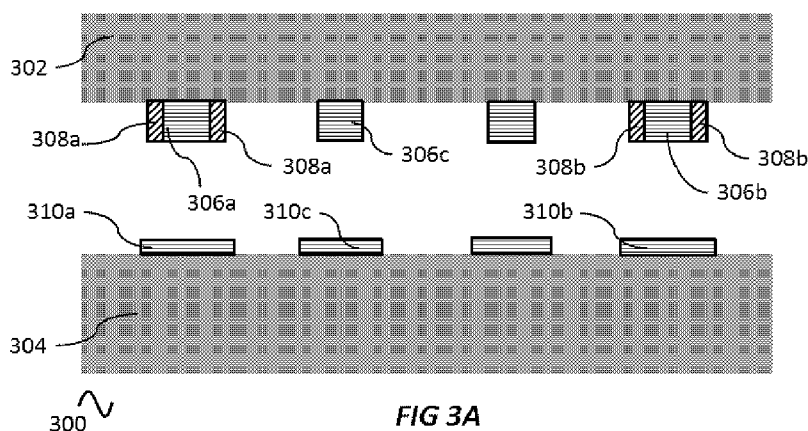


FIG 3A

(57) Abstract: A method for bonding a first substrate and a second substrate, the first substrate having at least one first connection extending from one side of the first substrate, the method comprising fabricating a first adhesive material around and along a height of the at least one first connection; and bonding the at least one first connection, the first adhesive material, and the second substrate.